

AMENDMENTS TO THE CLAIMS:

This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

1. (original) A complementary MISFET comprising:  
a first linear body including an N-type MISFET and a second linear body including a P-type MISFET; and  
a separation region arranged between said first linear body and said second linear body.
2. (original) The complementary MISFET of claim 1, wherein each cross section having a plurality of regions for forming said MISFET is continuously or intermittently formed in the longitudinal direction.
3. (previously presented) The complementary MISFET of claim 1, wherein said linear bodies and/or said separation region are formed of a material made of an organic semiconductor or electroconductive polymer.
4. (previously presented) An integrated circuit comprising the complementary MISFET of claim 1.
- 5-6. (canceled)
7. (original) An integrated circuit comprising:  
a plurality of linear bodies, each having a cross section which has a plurality of regions for forming a circuit

element formed in said linear body and which is continuously or intermittently formed in the longitudinal direction.

8. (original) The integrated circuit of claim 7, wherein said integrated circuit is a semiconductor memory, an image sensor, or a PLA.

9. (previously presented) The integrated circuit of claim 7, wherein said linear bodies are formed of a material made of an organic semiconductor or electroconductive polymer.

10. (previously presented) The integrated circuit of claim 4, wherein said linear body has a cross section in a circular, polygonal, star, crescent, petal, character shape, or another arbitrary shape.

11. (previously presented) The complementary MISFET of claim 2, wherein said linear bodies and/or said separation region are formed of a material made of an organic semiconductor or electroconductive polymer.

12. (previously presented) An integrated circuit comprising the complementary MISFET of claim 2.

13. (previously presented) An integrated circuit comprising the complementary MISFET of claim 3.

14-17. (canceled)

18. (previously presented) The integrated circuit of claim 8, wherein said linear bodies are formed of a material made of an organic semiconductor or electroconductive polymer.

19. (previously presented) The integrated circuit of claim 7, wherein said linear body has a cross section in a circular, polygonal, star, crescent, petal, character shape, or another arbitrary shape.

20. (previously presented) The integrated circuit of claim 8, wherein said linear body has a cross section in a circular, polygonal, star, crescent, petal, character shape, or another arbitrary shape.